44TH DESIGN AUTOMATION CONFERENCE

Only DAC offers:

- A robust technical program covering the latest research, developments and trends in electronic design, ranging from management practices to products, methodologies and technologies.
- Worldwide attendance from developers, designers, researchers, academics, managers and engineers from leading electronics companies and universities.
- A vibrant exhibition with 240 companies displaying products, technologies and services for the electronic design industry.

San Diego Convention Center • San Diego, California • June 4-8, 2007

ADVANCE PROGRAM

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Sponsored by:







ical Cooperation with







DAC: Where The Electronic Design Community Meets...

Dear Colleague:

Soon, thousands of us will converge in San Diego to attend the Design Automation Conference, the largest and most prestigious annual event focused on the design of electronic circuits and systems.

Who are we? We are the executives, managers, developers, designers, academics, journalists, venture capitalists, and others who make our industries and research groups the innovative, exciting, and productive drivers for the creation of electronic systems.

We will learn about the latest in design tools and methodologies for verification and test, design for manufacturing, IP, design libraries, RF/wireless, analog and mixed-signal designs, embedded software in SoCs, and other effects in today's designs. DAC is the place for the electronic design community to meet with:

• friends and renew acquaintances;

• colleagues and learn about the latest advances in tools, methodologies, fabrication, and test;

· vendors and learn about the latest product offerings;

• other designers and find out how they are using these tools to develop the next generation of ...

This year, we have 240 exhibitors, 201 technical presentations (including 8 on "Wild And Crazy Ideas"), plus 8 technical program panels, 18 pavilion panels, 7 full day tutorials, 6 hands-on tutorials, 7 workshops, and various co-located events.

Of particular interest to many of us will be the Automotive Theme, which highlights design challenges that stem from embedding electronic systems in engine control, driver interfaces, communications, entertainment, navigation, and safety critical systems in our automobiles. DAC will also feature a special Executive Management Seminar with management guru and best-selling author Geoffrey Moore, on the topic of managing innovation in our industry.

We finish the week with a tribute to the legacy of A. Richard Newton, Professor and Dean of the College of Engineering at the University of California, Berkeley, with a Thursday keynote by Jan Rabaey, the Donald O. Pederson Distinguished Professor at the University of California at Berkeley.

For more detailed conference information, visit us online at www.dac.com.

Please join us for an informative and inspiring week.



Best regards, Steve Levitan General Chair, 44th DAC

| Co-Located | The 44th Design Automation Conference Week in Review | | | | | | |
|--|--|--|--|--|------------------|------------------------------|--|
| Conferences | Sunday, June 3 | Monday, June 4 | Tuesday, June 5 | Wednesday, June 6 | Thursday, June 7 | Friday, June 8 | |
| • IWLS May 30 - June I, San Diego, CA • MSE 2007 June 2-4, San Diego, CA | • Four Workshops | Exhibits • Full-Day Tutorials • Hands-on Tutorials • Workshops • Keynote Address | General Session Keynote Address Technical Sessions Management Seminar Hands-on Tutorial Exhibits | Hands-on Tutorials Automotive Theme Sessions | | • Five Full-Day Tutorials | |

Networking Opportunities and Social Activities

Be sure to attend these DAC functions!

- * EDA Consortium Executive Reception, Sunday, 5:00pm 7:00pm
- * Exhibit Floor Happy Hour on Monday, 5:00pm 6:00pm
- ★ IEEE CEDA Distinguished Speaker Lecture, Monday, 6:00pm 8:00pm
- * SIGDA Ph.D Forum and Member Meeting, Tuesday, 6:30pm 8:00pm
- ★ Management Seminar on Tuesday, 10:30am 6:45pm

- * DAC Wednesday Night Party, 7:00pm 10:00pm. Enjoy great food, drinks and entertainment.
- * Mass Book Signing, Thursday, 11:00am 12:30pm
- *The DAC Pavilion in Booth 6360 on the exhibit floor there's always something going on!
- ★ Keynote Addresses on Monday, Tuesday and Thursday

DAC Technical Session Highlights...

This year's technical program consists of 161 selected papers out of 713 submissions, supplemented by 8 special sessions, 7 tutorials, 8 panels and 18 pavilion panels. The result is an exciting program, targeted to design engineers, management, developers and researchers, that showcases the latest advances in the field of electronic design automation.

The technical theme for this year's DAC is **automotive electronics**; an all-day track on Wednesday includes a special session, invited talks, a panel, and regular papers. Modern automobiles have an incredible array of electronic systems: engine management, satellite navigation, adaptive cruise control and many more. The increasing trend in automotive electronics shows few signs of abating. It has been estimated that electronics will account for as much as 40% of a car's bill-of-materials by the end of this decade. The modern car can now truly be described as a "networked computing platform," and the theme will highlight this issue in the context of electronic design automation.

The program this year includes a new **WACI** (Wild and Crazy Ideas) session, presenting early expositions of non-incremental ideas. The papers in this session encourage out-of-the-box thinking and are designed to promote discussions among attendees during and after the session.

The technical sessions are divided into eleven tracks: Analog/Mixed-Signal/RF and Simulation, Automotive Electronics, Business, DFM and the Manufacturing Interface, Interconnect and Reliability, Low Power Design, New and Emerging Technologies, Physical Design, Synthesis and FPGA, System Level and Embedded Design, and Verification and Test.

A major theme this year includes a strong focal point built around **system-level design**, including system-level communication issues aimed at designing the communication infrastructure of complex systems-on-chip, sessions that highlight industrial applications of ESL methods, MPSoC design, transaction level modeling, and 1000 core chips. Sessions in the area of **embedded systems** present the latest in embedded hardware and software design methods.

The **business track** is driven by an all-day track on Tuesday, beginning with a morning keynote, and continuing with an all-day **management seminar** presented by a group of luminaries: Geoffrey Moore, Raul Camposano and Jim Smith.

Design for manufacturability issues are prominent throughout the program, continuing a trend that has been active for several years now. In addition, there are sessions on process-aware physical design, statistical timing analysis, bridging the gap with silicon, and modeling the impact of technology on design. These are supplemented by special sessions on silicon measurement, and the design-manufacturing interface.

Low power is a prominent design consideration, and several sessions in the technical program focus on issues in this area. This year's selection of papers on power analysis and low power design covers a broad range of topics of wide interest for practical applications and workflows, with sessions dedicated to issues related to leakage power and implications of design variability on full-chip leakage power, on circuit-level approaches for low power design, and on tools and methodologies of interest to system-level design.

Another strong component of the program is in the area of **verification**. This year's program includes some outstanding papers on improving the verification process, ranging from theoretical results on the core computational engines of verification tools to practical, "best practice" case studies on the successful use of cutting-edge verification methodologies.

The technical paper presentations on Tuesday through Thursday are complemented by 7 **tutorial** presentations on Monday and Friday. These are presented by experts in the field, and cover themes such as DFM and variability, system level design, formal verification, reliability under soft errors, low power design, and power delivery concerns for die and package design. The 6 **hands-on tutorials** are in the area of DFM.

An array of **panels** spread throughout the program allow for free-form discussions headed by luminaries in the field, addressing emerging and important areas in the field of EDA. The panels cover topics such as EDA megatrends under shortening consumer cycles, handoffs between design and manufacturing, early power-aware design, transaction-level modeling, IP issues, multicore design, and challenges in functional verification. **Pavilion panels** on the exhibit floor lay the basis for more free-flowing and informal discussions. Topics of this year's panels include trends in EDA, managing mixed-signal designs, DFM, system-level wireless design, anticipating the next killer app, and many more.

44th Design Automation Conference®

Sunday, June 3 Workshops

- 4th UML for SoC Design Workshop 9:00am 5:30pm
- Low Power Coalition Workshop Standards for

Low Power Design Intent - 12:30pm - 3:30pm

Tuesday, June 5

- Design and Verification of Low Power ICs 4:00pm 7:00pm
- Hardware Dependent Software (HdS) 1:00pm 7:30pm

Exhibit Hours 9:00am - 6:00pm

EDA Consortium Executive Reception at the San Diego Marriott Hotel and Marina 5:00pm - 7:00pm

| Monday, June 4 Free Monday Exhibit Hours 9:00am - 6:00pm | | | | | | DAC Pavilion | |
|--|---|---|---|--|--|--|---|
| *** | | | | Booth #6360 | | | |
| | Rm: 6C | Rm: 6D | Rm: IIA | Rm: 6A | | | Gary Smith on EDA: Trends & What's Hot at DAC? |
| 9:00 | Tutorial I | Tutorial 2 | Hands-on Tutorial | | | | 9:30am - 10:30am |
| 10:00 | Anatomy of Variability and Making of "Variation | System Design for Multimedia Applications - | Standard Cell Library and Hard IP Design | | Workshop for Women | Introduction to Chips and EDA for a | EDA Exit Strategies: What's Next 10:45am - 11:45pm |
| | | Challenges, Design Methods | | | in Design Automation | Non-Technical Audience | Student Design Contest |
| 12:00 | Nanometer Technologies | and Recent Developments | Ponte Solutions | | 9:00am - 1:45pm • Room 8 | 10:00am - 12:00pm • Room 9 | Award Presentations 12:00pm - 1:00pm |
| 1:00 | Lunch (Rm: IAB) | Lunch (Rm: IAB) | | 3rd Integrated Design | | | |
| 2:00 | Tutorial I (cont.) Anatomy of Variability and | Tutorial 2 (cont.) | | Systems Workshop: | Monday Designing a New | Keynote | Hogan's Heroes: What We Hear and See in Optimized Timing and Power in 2007 2:00pm - 3:00pm |
| | Making of "Variation Tolerance" Vaccine in | Multimedia Applications - Challenges, Design Methods | Confidence ClearShape Technologies | Modeling Challenges are Touching Every Aspect of | Lawrence D. Burns - & Development and | Vice President of Research | Just Who is Providing the IP? 3:15pm - 4:00pm |
| 5:00 | | and Recent Developments | | IC Design | General M | otors Corp. Ballroom 20ABC | Anticipating the Next Killer App: Is There an iPhone in Your Future? 4:15pm - 5:00pm |

IEEE Council on EDA's Distinguished Speaker Lecture and Reception in the Sails Pavilion from 6:00pm - 8:00pm

| 8:30 to | reispective of the future semiconductor industry: chancinges and solutions | | | | | | | |
|---|--|---|---|---|--|--|---|--|
| 10:15 | | • | • | · · | inconductor business | | | |
| BREAK 10:15am - 10:30am Rm: 6B Rm: 6C Rm: 6D Rm: 6E Rm: 6F HOTS DAC Pavilion | | | | | | | | |
| | Session I | Session 2 | Session 3 | Session 4 | Session 5 | | Booth #6360 | |
| 10:30 to 12:00 | SPECIAL SESSION: Trusted Hardware | PANEL SESSION: Mega Trends and EDA 2017 | Industrial Application of System Level Methods | Novel Techniques for Interconnect | Formal & Semi-Formal Verification Techniques | m nization stems, Inc. | Career Advancement for Technologists: An Interview with the Marie R. Pistilli Woman in EDA Award Winn 10:15am - 11:00am | |
| | | LU | JNCH 12:00pm - 2:00pr | m | | Syling. | Managing Mixed-Signal | |
| | Session 6 | Session 7 | Session 8 | Session 9 | Session 10 | 1 8 4 8 1 0 8 | Designs: What's Working? | |
| 2:00 to 4:00 | Leakage Power Analysis & Optimization | PANEL SESSION: Making Manufacturing Work for You | Energy & Performance Issues in On-Chip Communication Networks | Circuit Simulation | Signal & Power Delivery Integrity | atistical Timi o Analysis an on/Codence D | What's Missing? 11:15am - 12:00pm Deploying Formal: When and Where? 2:00pm - 3:00pm | |
| | | | REAK 4:00pm - 4:30pm | 1 | | on t | , | |
| | Session I I | Session 12 | Session 13 | Session 14 | Session 15 | riginal i | ESL for Wireless | |
| 4:30 to 6:30 | SPECIAL SESSION: Functional Verification of ESL Models | PANEL SESSION: Early Power-Aware Design and Validation | Memories in Embedded Systems | Statistical Techniques for Timing Analysis and Design | SPECIAL SESSION: Wild And Crazy Ideas | Deploying Statistical Timing – from Characterization to Analysis and Optimization Altos Design Automotion/Coderce Design Systems, Inc. | 3:15pm - 4:15pm To Be or Not To Be Complia That is the Question 4:30pm - 5:30pm | |
| | SIG | DA Ph.D. Forum and Memi | ber Meeting in the Sails Pa | vilion from 6:30pm - 8:00 | pm | | | |
| | Wednesday, Ju | ıne 6 | | Exhibit Hou | urs 9:00am - 6:00p | m | | |
| | Rm: 6B | Rm: 6C | Rm: 6E | Rm: 6F | Rm: 6A | HOTs | DAC Pavilion | |
| | Session 16 | Session 17 | Session 18 | Session 19 | Session 20 | a . | | |
| 8:30 to 10:00 | Distributed Computing: Automotive Network Design & Analysis | Emerging Nanoscale Hybrid Circuits & Architectures | Physical Implementation of FPGAs | Process Aware Physical Design | Reliable Design & CAD Solutions for Circuit Aging | Approaching Yield in the Nanometer Age, Mentor Graphis Cop./ Grantered Semicorductor Mandfacturing/ Sierra Design Automotion, thc./ARM Ltd. | The Urban Challenge: Paving the Way for | |
| | | BR | EAK 10:00am - 10:30a | am | | 1 = 6 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 | Driverless Automobiles | |
| | Session 21 | Session 22 | Session 23 | Session 24 | Session 25 | | 9:30am - 10:15am | |
| 10:30 to 12:00 | INVITED SESSION: Silicon, Safety and Self-Driving Cars | SPECIAL SESSION: Silicon Measurement Correlation to Reliability | Optimizing Arithmetic & Communication | Analog & RF Simulation | PANEL SESSION: TLM: Crossing Over from Buzz to Adoption | Proaching Yi Age: Mer Chartered Senik Sierra Design A | Improving Automotive Competitiveness: New Metho and Tools For Embedded Des 11:00am - 12:00pm | |
| | | LU | NCH I 2:00pm - 2:00p | m | | 4₹ | Electronics: The Key to Disruption of Automobile | |
| | Session 26 | Session 27 | Session 28 | Session 29 | Session 30 | σō | Powertrain Technology | |
| 2:00 to 4:00 | PANEL SESSION: Electronics: The New Differential in the Automotive Industry | Modern Placement Techniques | Advances in Embedded Hardware Design | Bridging the Gap with Silicon | Practical Solutions for Power-Aware Testing | Manufacturing Aware Optimization Blaze DFM, Inc. Taiwan Semiconductor Manufacturing Company, Itd. | DFM: Prevention or Cure 2:00pm - 3:00pm | |
| | , | R | REAK 4:00pm - 4:30pr | m | | Cor | On a Crash Course: Validation a | |
| | Session 3 I | Session 32 | Session 33 | Session 34 | Session 35 | _ \\$\colon \colon \col | Testing of Automotive Software 3:15pm - 4:15pm | |
| 4:30 to 6:30 | SPECIAL SESSION: Virtual Automotive Platforms | SPECIAL SESSION: The Future of Interconnects | Advances in Decision Procedures | 3D IC & Package Design Issues | PANEL SESSION: Corezilla: Build and Tame the Multicore Beast | fanufacturing fæe DFM, Inc Manufact | The One Ton Mobile Platfor Where is it Taking Us? 4:30pm - 5:30pm | |

San Diego, CA, June 4 - 8, 2007

| | Thursday, | June 7 | | Exhibit Hours 9:00am - 1:00pm | | | |
|---------------------|---|---|---|---|---|---|---|
| | Rm: 6B | Rm: 6C | Rm: 6D | Rm: 6E | Rm: 6F | Rm: 6A | Hands On Tutorial |
| | Session 36 | Session 37 | Session 38 | Session 39 | Session 40 | Session 41 | Timing Closure: Requirements for |
| 9:00 to 11:00 | SPECIAL SESSION: Synthetic Biology | Programming & Scheduling Embedded Systems | Emerging Test Solutions | Circuit Level Power Analysis & Low Power Design | Parameter Tuning in System Architecture Exploration | PANEL SESSION: Verification Coverage: When is Enough Enough? | Variation Aware Design Extreme DA Corp./ Texas Instruments Inc./ PDF Solutions/UMC 9:00am - 12:00pm |
| | | | LUNCH II:00 | am - 12:30pm | | | DAC Pavilion |
| | Be | st Paper Award F | resentations and | l Keynote Speake | r Ballroom 20 | ABC | Booth #6360 |
| 12:30 to 1:45 | | | | | A. Richard Newt ersity of California, Berk | | P-cells or Free Cells 10:15am - 11:15am |
| | Session 42 | Session 43 | Session 44 | Session 45 | Session 46 | Session 47 | |
| 2:00 to 4:00 | SPECIAL SESSION: Thousand-Core Chips | Communication- Based Resource Allocation | Embedded Processor & MPSoC Design | Modeling Technology Impact | Technology Mapping & Physical Synthesis | System-Level Power Management & Analysis | |
| | | | BREAK 4:00 | pm - 4:30pm | | | |
| | Session 48 | Session 49 | Session 50 | Session 5 I | Session 52 | Session 53 | |
| 4:30 to 6:00 | Dynamic Verification of Processors & Processor-Based Designs | FPGA Tools & Methodologies | Mixed-Signal Modeling, Methodology & Synthesis | Design Methods & Manufacturability Solutions for Emerging Technologies | High-Performance Synchronization Techniques | PANEL SESSION: IP Exchange | |

Friday, June 8 Full-Day Tutorials

| | Rm: 6F | Rm: 6A | Rm: 6C | Rm: 6D | Rm: 6E |
|--------------------|--|---|--|--|--|
| 9:00 to 5:00 | TUTORIAL 3 Formal Assertion Based Verification in an Industrial Setting | TUTORIAL 4 Design and Analysis of High- Performance Package and Die Power Delivery Networks | TUTORIAL 5 Soft Errors:Technology Trends, System Effects and Design Techniques | TUTORIAL 6 How Design Meets Yield in the Fab | TUTORIAL 7 Circuit and CAD Techniques for Low Power Design |

Keynote, Monday, June 4 • 2:00pm - 3:00pm • Ballroom 20ABC

Designing a New Automotive DNA Lawrence D. Burns

Vice President of Research & Development and Strategic Planning, General Motors Corp.

The automotive industry stands on the threshold of a new opportunity — an opportunity that stems from the reinvention of the automobile using a new DNA that exchanges the internal combustion engine, petroleum, and mechanical linkages for fuel cells and batteries, hydrogen and electricity, and electronic systems and controls.

Electrically driven vehicles and the introduction of advanced electronics and connected vehicle technologies will revolutionize how our vehicles operate, how we interact with them, and how

they communicate with each other and the outside world. These new technologies will also, importantly, dramatically dange how automobiles are designed and built.

In this talk, Dr. Burns will highlight why the new automotive DNA will be paradigm shifting for the industry and address the design challenges and opportunities presented by the requirement for new electrical and electronics-based architectures, systems, and software for our vehicles.

Keynote, Tuesday, June 5 • 8:30am - 10:15am • Ballroom 20ABC

Perspective of the Future Semiconductor Industry: Challenges and Solutions Oh-Hyun Kwon

President, System LSI Division, Samsung Semiconductor Business

The semiconductor industry currently faces serious challenges and changes on both the business and technology fronts. The business environment is becoming more difficult. The huge investment required for new fabrication facilities is forcing many IDMs (Integrated D evice Marufacturer) to change their business model to either fablite or fabless. The significant costs to develop the next generation process technologies are necessitating joint development between various companies. Furthermore due to seve re competition in the mobile and digital consumer markets, low chip prices and short time-to-market are both essential for survival. To satisfy these market requirements, heavy R&D expenses and resources are needed. However, its return on investment is becoming marginal and even uncertain. To overcome this difficult situation, the industry is experiencing consolidation of once proudly independent

companies. On the technical side, controlling chip yield, power consumption and design complexity have become extremely difficult in the nano-technology era.

This talk will present a perspective on how the semiconductor industry must respond to these challenges by developing new markets, n ew products, and new technologies. The solutions will come from (i) collaborations with key customers for new markets and products, as well as, with key partners for new technologies, and (ii) technology breakthroughs with imovative ideas, such as 3-D package, fusion technologies (OneDRAM™, OneNAND™), variation-tolerant designs, and low leakage devices. These app roaches can lead to lower chip costs and relieve physical uncertainty problems.

Keynote, Thursday, June 7 • 12:30pm - 1:45pm • Ballroom 20ABC



Design without Borders – A Tribute to the Legacy of A. Richard Newton Jan M. Rabaey

Donald O. Pederson Distinguished Professor, Director Gigascale Systems Research Center (GSRC), Scientific Co-director BWRC, University of California, Berkeley

Electrical engineers have learned how to build amazingly complex systems by assembling transistors, wires, and passive components into intricate networks. While solidly founded in semiconductor physics, pure engineering has made possible the design of multi-billion transistor chips in a repetitive reliable and cost-effective way. A comprehensive "design methodology" was developed based on modularization, hierarchy and abstraction.

Today this story is repeating itself. Physicists, chemists and biologists are exploring entirely different components such as molecules, atoms, and enzymes. Systems built from those will most probably

impact our lives and society in a profound way. Outcomes will influence the ways we build mechanical structures, do computing, make drugs, generate energy and take care of our environment.

Yet, while the basic components are dramatically different from our silicon devices, the basic strategyfor building very complex systems from them remains unchanged. The art of design, as was developed in the silicon era, is just as applicable to these nano- or bio-constructions. Design methodology is a legacy that will live long after Moore's Law has come to a halt. To quote Richard, "The Future is BDA (Bio Design Automation)".

Management Seminar - Tuesday, June 5 • 10:30am - 6:45pm • Rm: 6A

Innovation or Extinction - The Choice Is Yours!

Innovation is critical for the long term success of any industry. The electronics, semiconductor and the electronic design automation industry have pursued such a strategy successfully for several decades. This was made possible by technological advances in processing, innovative design flows and methodologies, and continued improvement in design tools. However limitations in manufacturing, increasing design complexity and design costs have started to decelerate the possible gains obtained along these directions. In the recent past, growth in these industries has slowed and it is perceived by many that these industries need to do more to capture growth. In

This seminar is designed for middle and senior management who wish to consider innovation as a part of strategic planning. The seminar is structured in three parts:

- 1. Innovative Fundamentals, Speaker: Geoffrey Moore TCG Advisors, San Mateo, CA
- 2. Innovation in the Semiconductor and Electronic Design Automation Markets, Speaker: Raul Camposano Xoomsys, Inc., Cupertino, CA
- 3. Investing for Innovation, Speaker: Jim Smith Mohr Davidow Ventures, Menlo Park, CA

addition, the twin forces of globalization and technology have led to changes that impact business dramatically. Globalization has enabled vast and eager talent pools to participate in business at low cost. Technology has lowered the barriers to market entry and leveled the playing field in many situations. In the current scenario, innovation is not only key but perhaps the only method to differentiate your business from that of your competitors. Registration for this event includes: entrance to the Keynotes, entrance to the Exhibition, a copy of the book "Dealing with Darwin", coffee breaks, and the Productivity Impact Luncheon (produced by EDA Consortium and FSA).

Productivity Impact Luncheon - Changing the Dialogue Between Engineers & Management

Produced by the EDA Consortium and FSA Date: Tuesday, June 5, Noon to 1:30 pm Admission: \$50 early registration, \$60 after May 7

Speakers: Kathryn Kranen, Brian Fuller, Lisa Tafoya

Automotive Electronics at DAC

There has been an explosion of electronic content in automobiles recently. For 2007, the automotive semiconductor market is expected to be \$19 billion (Gartner/Dataquest) and by 2010 it is expected that 40% of the bill of materials in cars will be for electronics. The Automotive theme addresses how design tools and methodologies will be used to support the tremendous design requirements for automotive electronics and what role EDA will play.

Attendees will have a chance to "look under the hood" of two cars that represent the future of automotive electronics: the GM Sequel Hydrogen car and the Wrightspeed XI prototype electric car with a few lucky attendees getting a chance to test drive the Sequel Hydrogen car.

Technical presentations from experts representing leading electronics and automotive suppliers include a Keynote address by Larry Burns, Vice President Research & Development and Strategic Planning for General Motors. Other technical presentations include sessions on Automotive Electronics as a major product differentiator, the network protocols for distributed architectures, safety issues including robust design, and the validating and testing of automotive software. Additional sessions address the use of virtual platforms to reduce MCU count, embedded systems design as a competitive advantage, and how the changing requirements of the automotive market will affect the R&D agendas of semiconductor and EDA companies.

DAC Pavilion on the Exhibit Floor Booth #6360

DAC has an exciting line-up of panels and presentations in the DAC Pavilion on the exhibit floor. The DAC Pavilion sessions are open to all attendees and feature provocative technical, business, and strategy discussions.

| DAC PAVILION DAY | TIME | DAC PAVILION DAY | TIME |
|---|-------------------|--|-------------------------------------|
| Gary Smith on EDA: Trends & What's Hot at DAC? Mon., June 4 | 9:30am - 10:30am | ESL for WirelessTues., June | 3:15pm - 4:15pm |
| EDA Exit Strategies: What's Next? | 10:45am - 11:45am | To Be or Not To Be Compliant: That is the Question .Tues., June | |
| Student Design Contest Award Presentations | 12:00pm - 1:00pm | The Urban Challenge: Paving the Way for | |
| Hogan's Heroes: What We Hear and See in | | Driverless Automobiles | 6 9:30am - 10: <mark>15am</mark> |
| Optimized Timing and Power in 2007Mon., June 4 | 2:00pm - 3:00pm | Improving Automotive Competitiveness: | |
| Just Who is Providing the IP? | 3:15pm - 4:00pm | New Methods and Tools for Embedded DesignWed., June | 6 11:00am - 12 <mark>:00pm</mark> |
| Anticipating the Next Killer App: | | Electronics: The Key to Disruption | |
| Is There an iPhone in Your Future? | 4:15pm - 5:00pm | of Automobile Powertrain Technology | 6 1:00pm - 1:4 <mark>5pm</mark> |
| Career Advancement for Technologists: An Interview with the | | DFM: Prevention or Cure | 6 2:00pm - 3:0 <mark>0pm</mark> |
| Marie R. Pistilli Woman in EDA Award WinnerTues., June 5 | 10:15am - 11:00am | On a Crash Course: Validation and Testing | |
| Managing Mixed-Signal Designs: | | of Automotive Software | 6 3:15pm - 4:15pm |
| What's Working? What's Missing?Tues., June 5 | 11:15am - 12:00pm | The One Ton Mobile Platform: Where is it Taking Us? . Wed., June | 6 4:30pm - 5:30 <mark>pm</mark> |
| Deploying Formal: When and Where? Tues., June 5 | 2:00pm - 3:00pm | P-cells or Free Cells | 7 |

44th DAC Workshops

4th UML for SoC Design Workshop Sunday, June 3, 9:00am - 5:30pm

Low Power Coalition Workshop -Standards for Low Power Design Intent Sunday, June 3, 12:30pm - 3:30pm

Design and Verification of Low Power ICs Sunday, June 3, 4:00pm - 7:00pm

Hardware Dependent Software (HdS) Sunday, June 3, 1:00pm - 7:30pm Introduction to Chips and EDA for a Non-Technical Audience

Monday, June 4, 10:00am - 12:00pm

Workshop for Women in Design Automation - Managing Your Career

Monday, June 4, 9:00am - 1:45pm

3rd Integrated Design Systems Workshop

Monday, June 4, 12:00pm - 5:00pm

Exhibition

The 44th DAC Exhibition is located on the main floor of the San Diego Convention Center

The 44th exhibit floor is bursting with 240 vendors offering products for all phases of the electronic design process including EDA tools, IP cores, embedded system and system-level tools, as well as silicon vendors and design-for-manufacturing companies. The DAC show floor features its unique exhibit booth and private suite combination, which gives you the freedom to deeply explore the products on the show floor and find a solution that is right for your design flow. Visit the DAC exhibition and find out how you can improve performance and shorten the time-to-market on your next design.

Attend Free Monday, June 4, 2007

Exhibit Hours

Monday-Wednesday, June 4-6 Thursday, June 7 9:00am - 6:00pm 9:00am - 1:00pm

Exhibiting Companies (as of April 27, 2007)

Accelicon Technologies, Inc. ACE Associated Compiler Experts by Advantest Technology Solutions Agilent Technologies Aldec, Inc. Algotronix Ltd. Algotronix Ltd.
Altos Design Automation
Analog Bits Inc.
Analog Rails
Anasift Technology, Inc.
Anchor Semiconductor, Inc.
Anchor Semiconductor, Inc.
Apache Design Solutions, Inc.
Applied Simulation Technology
Applied Wave Research, Inc.
Appro International
Arasan Chip Systems
ArchPro Design Automation, In ArchPro Design Automation, Inc. Artwork Conversion Software, Inc. Athena Design Systems Atoptech Atrenta Inc. Attachmate austriamicrosystems
AutoESL Design Technologies Inc. Averant, Inc. Avery Design Systems, Inc. Axiom Design Automation Axion Design Automation
Azuro, Inc.
Beach Solutions Ltd.
Berkeley Design Automation, Inc.
Blaze DFM, Inc.
Blue Pearl Software Bluespec, Inc. Breker Verification Systems Brion Technologies
BullDAST s.r.l.
CAD Science, Inc.
Cadence Design Systems, Inc.
Calypto Design Systems
Carbon Design Systems, Inc.
CAST Inc. CAST, Inc.
Center for Embedded Computer Systems Certess Inc.
Chip Estimate Corp.
ChipVision Design Systems Ciranova, Inc. Clear Shape Technologies, Inc. CLK Design Automation, Inc. CoFluent Design CommandCAD, Inc. Command AD, Inc. Concept Engineering GmbH Coupling Wave Solutions CoWare, Inc. CRC Press - Taylor & Francis Critical Blue DAC Pavilion Dataram DATE '08 DeFacTo Technologies Denali Software, Inc. Design and Reuse Dini Group (The) Dolphin Integration Dynalith Systems Co., Ltd. EDXACT Elsevier EMA Design Automation, Inc. eMemory Technology Inc. ENOVIA MatrixOne Entasys Design, Inc. Envision Technology

Extreme DA Fenix Design Automation FishTail Design Automation Flomerics, Inc Forte Design Systems Fortelink Inc. FTL Systems, Inc. Gaisler Research AB GateRocket, Inc. Genesys Testware, Inc. Gidel Inc. Golden Gate Technology, Inc. Gradient Design Automation Handshake Solutions HARDI Electronics AB Helic S.A Heller Ehrman Hewlett-Packard Co. Hummingbird Connectivity - Open Text IBM Corp.
IC Manage IEEE Spectrum IMEC Imperas, Inc.
Incentia Design Systems, Inc.
Innovative Silicon Inc. Innovative Silicon Inc.
InsideChips.com
Intel Corp.
Intellitech Corp.
InternetCAD.com, Inc.
Interra Systems, Inc.
Iasper Design Automation, Inc.
Javelin Design Automation, Inc.
JEDA Technologies
KETI / IP SoC Support Center
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